

XMS Series Connectors

Soldering Profile. DATE:2010/09/28 R(REV:A3)

Solder Reflow profile for Lead-Free packages. Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.($T_{s \text{ min.}}$) Temperature Max.($T_{s \text{ max.}}$) Time (min to max) (t_s)	150 °C 200 °C 60-180 sec	
$T_{s \text{ max.}}$ to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Temperature (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

Profile

